

# ASI #104 Heat Sink Compound

## Description

ASI #104 Heat Sink Compound is a non dripping, thermally conductive grease to reduce thermal impedance of the air gap otherwise present between the mating surfaces of a semi-conductor and heat sink. ASI #104 is also used in automotive temperature sensing devices.

ASI #104 has excellent thermal resistance of only 00.05C/W for a 0.001" film, with an area of one square inch. It will not harden, dry out, or melt of 200°C.

PROPERTIES	
Appearance	Opaque White
Specific Gravity	2.45 x 25°C, 20.4 #/gallon
Volume Resistivity	2.0 x 10 (15) ohm/cm
Dielectric Strength	450 volts/mil
Thermal Conductivity	.00177 gm cal/sec cm@1C/cm (5.1 BTU/hr ft. (20) F/in)
Thermal Resistivity(p)	56°C in/watt
Bleed, percent	0.0 after 24 hrs. at 200°C
Evaporation, percent	0.5 after 24 hours at 200°C
Press Flow, .105 Orifice	13 sec ± 2 at 42.5 psi, 25°C
Worked Penetration	260-340, 60 Strokes

**Shelf Life:** Stored at ambient temperatures, shelf life is 12 months from date of manufacture

## Warranty Limitations

ASI warrants only that its products will meet its specifications. ASI shall in no event be liable for incidental or consequential damages. Except as expressly stipulated, ASI's liability, expressed or implied is limited to the stated selling price of any defective goods.